

PROCESSING METHOD, METHOD OF MANUFACTURING SEMICONDUCTOR
DEVICE, PROCESSING APPARATUS, AND PROGRAM

ABSTRACT

A technique includes: (a) providing a state where a product substrate and a nitrogen-containing object are disposed in a process container; and (b) etching a surface of the product substrate by using a substance X produced by supplying a fluorine-containing substance into the process container in which the product substrate and the nitrogen-containing object are disposed and causing the nitrogen-containing object to chemically react with the fluorine-containing substance.

Fig. 4